

# BU808DFH

## HIGH VOLTAGE FAST-SWITCHING NPN POWER DARLINGTON TRANSISTOR

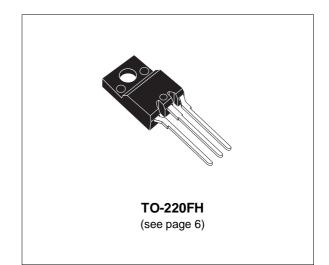
- NEW Fully Plastic TO-220 for HIGH VOLTAGE APPLICATIONS
- NPN MONOLITHIC DARLINGTON WITH INTEGRATED FREE-WHEELING DIODE
- HIGH VOLTAGE CAPABILITY ( > 1400 V )
- HIGH DC CURRENT GAIN (TYP. 150)
- LOW BASE-DRIVE REQUIREMENTS
- DEDICATED APPLICATION NOTE AN1184
- FULLY INSULATED PACKAGE (U.L. COMPLIANT) FOR EASY MOUNTING
- CREEPAGE PATH > 4 mm

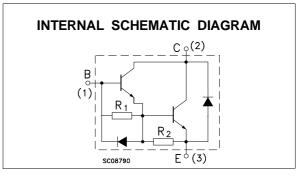
## **APPLICATIONS**

 COST EFFECTIVE SOLUTION FOR HORIZONTAL DEFLECTION IN LOW END TV UP TO 21 INCHES.

## DESCRIPTION

The BU808DFH is a NPN transistor in monolithic Darlington configuration. It is manufactured using Multiepitaxial Mesa technology for cost-effective high performance.





## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vсво	Collector-Base Voltage (I <sub>E</sub> = 0)	1400	V
Vceo	Collector-Emitter Voltage $(I_B = 0)$	700	V
$V_{EBO}$	Emitter-Base Voltage (I <sub>C</sub> = 0)	5	V
Ιc	Collector Current	8	A
I <sub>CM</sub>	Collector Peak Current (t <sub>p</sub> < 5 ms)	10	A
Ι <sub>Β</sub>	Base Current	3	A
I <sub>BM</sub>	Base Peak Current (t <sub>p</sub> < 5 ms)	6	A
Ptot	Total Dissipation at $T_c = 25 \ ^{\circ}C$	42	W
Visol	Insulation Withstand Voltage (RMS) from All Three Leads to Exernal Heatsink	2500	V
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

## THERMAL DATA

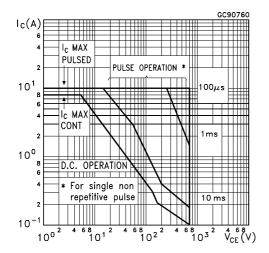
Rthj-case Thermal Resistance Junction-case	Max	2.98	°C/W
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## **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25 \ ^{\circ}C$ unless otherwise specified)

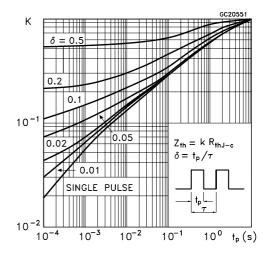
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
ICES	Collector Cut-off Current (V <sub>BE</sub> = 0)	V <sub>CE</sub> = 1400 V			400	μA
I <sub>EBO</sub>	Emitter Cut-off Current $(I_c = 0)$	V <sub>EB</sub> = 5 V			100	mA
V <sub>CE(sat)</sub> *	Collector-Emitter Saturation Voltage	$I_{\rm C} = 5 \ {\rm A}$ $I_{\rm B} = 0.5 \ {\rm A}$			1.6	V
V <sub>BE(sat)</sub> *	Base-Emitter Saturation Voltage	$I_{\rm C} = 5 \text{ A}$ $I_{\rm B} = 0.5 \text{ A}$			2.1	V
h <sub>FE</sub> *	DC Current Gain		60 20		230	
t <sub>s</sub> t <sub>f</sub>	INDUCTIVE LOAD Storage Time Fall Time				3 0.8	μs μs
t <sub>s</sub> t <sub>f</sub>	INDUCTIVE LOAD Storage Time Fall Time			2 0.8		μs μs
VF	Diode Forward Voltage	I <sub>F</sub> = 5 A			3	V

\* Pulsed: Pulse duration =  $300 \,\mu$ s, duty cycle 1.5 %

## Safe Operating Area

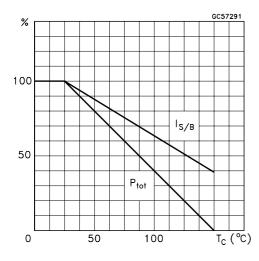


## Thermal Impedance

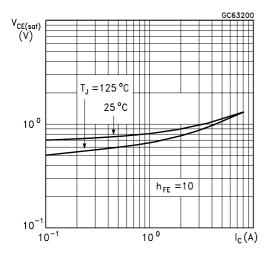


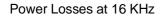
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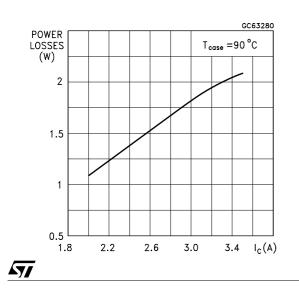
## **Derating Curve**



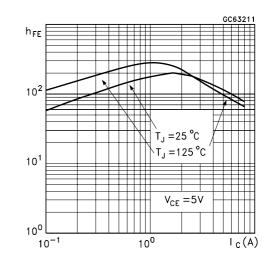
Collector Emitter Saturation Voltage



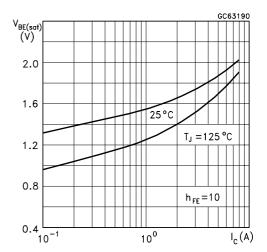


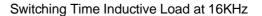


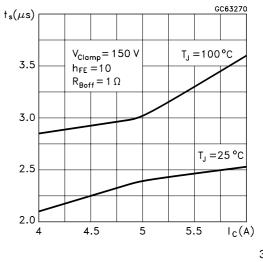
DC Current Gain

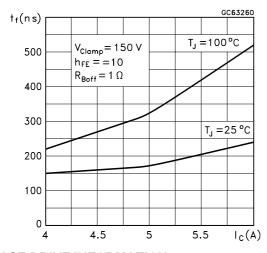


## Base Emitter Saturation Voltage









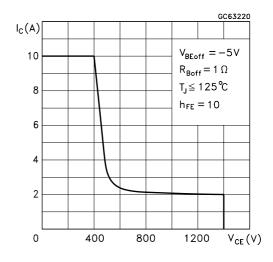
Switching Time Inductive Load at 16KHZ

#### **BASE DRIVE INFORMATION**

In order to saturate the power switch and reduce conduction losses, adequate direct base current  $I_{B1}$  has to be provided for the lowest gain  $h_{FE}$  at 100 °C (line scan phase). On the other hand, negative base current  $I_{B2}$  must be provided to turn off the power transistor (retrace phase).

Most of the dissipation, in the deflection application, occurs at switch-off. Therefore it is essential to determine the value of  $I_{B2}$  which minimizes power losses, fall time  $t_f$  and, consequently,  $T_{j.}$  A new set of curves have been defined to give total power losses,  $t_s$  and  $t_f$  as a function of  $I_{B2}$  at both 16 KHz scanning frequencies for choosing the optimum negative

**Reverse Biased SOA** 



drive. The test circuit is illustrated in figure 1.

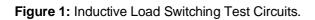
Inductance  $L_1$  serves to control the slope of the negative base current  $I_{B2}$  to recombine the excess carrier in the collector when base current is still present, this would avoid any tailing phenomenon in the collector current.

The values of L and C are calculated from the following equations:

$$\frac{1}{2} L (I_C)^2 = \frac{1}{2} C (V_{CEfly})^2 \qquad \omega = 2 \pi f = \frac{1}{\sqrt{LC}}$$

Where I<sub>C</sub>= operating collector current, V<sub>CEfly</sub>= flyback voltage, f= frequency of oscillation during retrace.

**LT** 



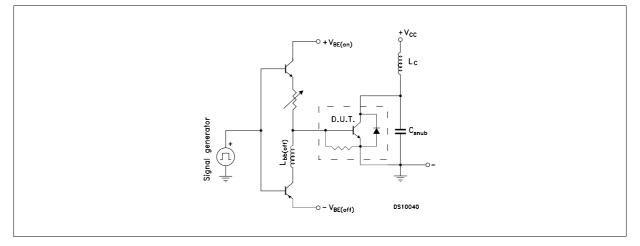
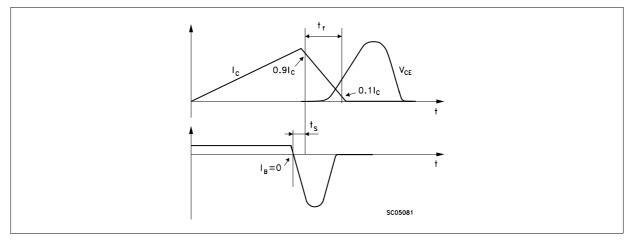
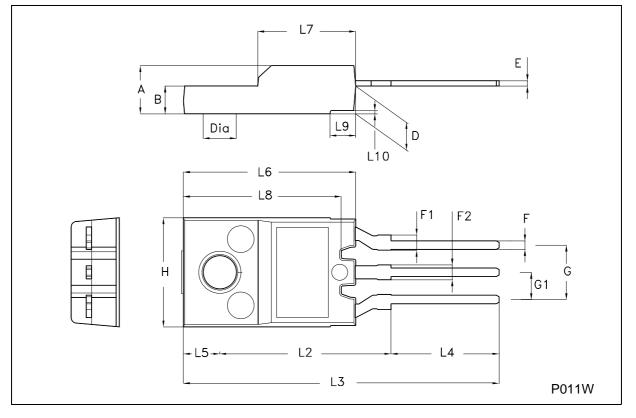


Figure 2: Switching Waveforms in a Deflection Circuit



DIM.		mm		inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
Е	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.3		1.8	0.051		0.070
F2	1.3		1.8	0.051		0.070
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L5		3.4			0.134	
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
L8	14.5		15	0.570		0.590





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